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E 42/21/20 Core and accessories

Series/Type: B66329, B66243

Date: May 2017

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Core B66329

■ To IEC 62317-8

■ Delivery mode: single units

Magnetic characteristics (per set)

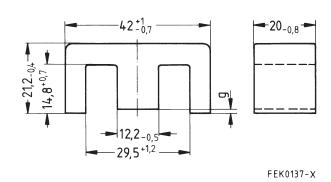
 $\Sigma I/A = 0.41 \text{ mm}^{-1}$

= 97 mm

 $= 234 \text{ mm}^2$

 $A_{min} = 229 \text{ mm}^2$

 $= 22700 \text{ mm}^3$



Approx. weight 116 g/set

Ungapped

Mate- rial	A _L value nH	μ _e	B _S * mT	P _V W/set	Ordering code
N27	4750 +30/–20%	1560	320	< 4.40 (200 mT, 25 kHz, 100 °C)	B66329G0000X127
N87	5200 +30/–20%	1690	320	< 12.00 (200 mT, 100 kHz, 100 °C)	B66329G0000X187
N97	5400 +30/–20%	1781	320	< 10.20 (200 mT, 100 kHz, 100 °C)	B66329G0000X197
N95	6700 +30/–20%	2292	320	< 12.60 (200 mT, 100 kHz, 25 °C) < 11.50 (200 mT, 100 kHz, 100 °C)	B66329G0000X195

^{*} H = 250 A/m; f = 10 kHz; T = 100 °C

Gapped (A_L values/air gaps examples)

Material	g mm	A _L value approx. nH	μ_{e}	Ordering code ** = 27 (N27) = 87 (N87)
N27,	0.25 ±0.02	1029	338	B66329G0250X1**
N87	0.50 ±0.05	603	198	B66329G0500X1**
	1.00 ±0.05	354	116	B66329G1000X1**
	1.50 ±0.05	259	85	B66329G1500X1**

The A_1 value in the table applies to a core set comprising one ungapped core (dimension g = 0 mm) and one gapped core (dimension g > 0 mm).

Other A_L values/air gaps and materials available on request – see Processing remarks on page 6.



Core B66329

Calculation factors (for formulas, see "E cores: general information")

Material	Relationship between air gap – A _L value		Calculation o	f saturation cu	uration current	
	K1 (25 °C)	K2 (25 °C)	K3 (25 °C)	K4 (25 °C)	K3 (100 °C)	K4 (100 °C)
N27	354	-0.770	574	-0.847	534	-0.865
N87	354	-0.770	555	-0.796	521	-0.873

Validity range: K1, K2: 0.10 mm < s < 3.00 mm

K3, K4: 160 nH < A_L < 1500 nH



Accessories B66243

Coil former

Material: GFR polyterephthalate (UL 94 V-0, insulation class to IEC 60085:

F

max. operating temperature 155 °C), color code black

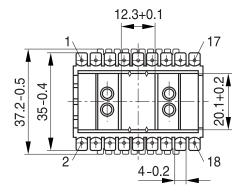
Valox 420-SE0 [E121562 (M)] SABIC INNOVATIVE PLASTICS US L L C

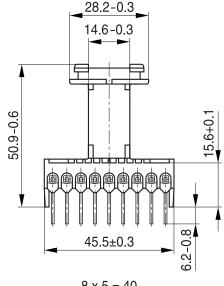
Solderability: to IEC 60068-2-20, test Ta, method 1 (aging 3): 235 °C, 2 s

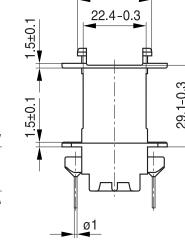
Resistance to soldering heat: to IEC 60068-2-20, test Tb, method 1B: 350 °C, 3.5 s

Winding: see Processing notes, 2.1

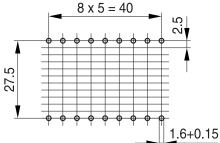
Sections	A _N mm ²	I _N mm	A_R value $\mu\Omega$	Pins	Ordering code
1	172	100	20	18	B66243B1018T001







26.5-0.3



Hole arrangement View in mounting direction

FEK0512-2-E



Accessories B66243

Coil former

Material: Polyterephthalate GV (UL 94 V-0, insulation class to IEC 60085:

H ≙ max. operating temperature 180 °C), color code black

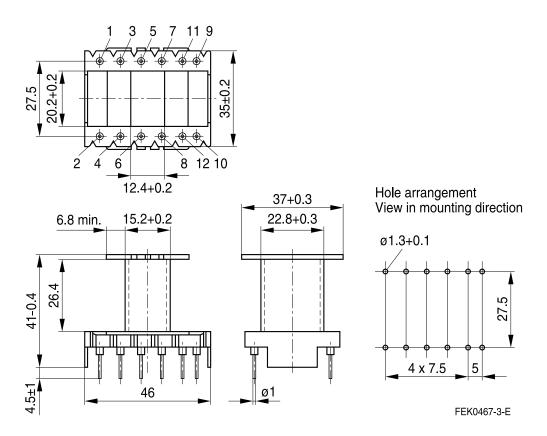
Rynite FR 530® [E41938 (M)], E I DUPONT DE NEMOURS & CO INC

Solderability: to IEC 60068-2-20, test Ta, method 1 (aging 3): 235 °C, 2 s

Resistance to soldering heat: to IEC 60068-2-20, test Tb, method 1B: 350 °C, 3.5 s

Winding: see Processing notes, 2.1

Sections	A _N mm ²	I _N mm	A_R value $\mu\Omega$	Pins	Ordering code
1	187	133	24.4	12	B66243S1012T001





Cautions and warnings

Mechanical stress and mounting

Ferrite cores have to meet mechanical requirements during assembling and for a growing number of applications. Since ferrites are ceramic materials one has to be aware of the special behavior under mechanical load.

As valid for any ceramic material, ferrite cores are brittle and sensitive to any shock, fast temperature changing or tensile load. Especially high cooling rates under ultrasonic cleaning and high static or cyclic loads can cause cracks or failure of the ferrite cores.

For detailed information see data book, chapter "General - Definitions, 8.1".

Effects of core combination on A_I value

Stresses in the core affect not only the mechanical but also the magnetic properties. It is apparent that the initial permeability is dependent on the stress state of the core. The higher the stresses are in the core, the lower is the value for the initial permeability. Thus the embedding medium should have the greatest possible elasticity.

For detailed information see data book, chapter "General - Definitions, 8.1".

Heating up

Ferrites can run hot during operation at higher flux densities and higher frequencies.

NiZn-materials

The magnetic properties of NiZn-materials can change irreversible in high magnetic fields.

Ferrite Accessories

EPCOS ferrite accessories have been designed and evaluated only in combination with EPCOS ferrite cores. EPCOS explicitly points out that EPCOS ferrite accessories or EPCOS ferrite cores may not be compatible with those of other manufacturers. Any such combination requires prior testing by the customer and will be at the customer's own risk.

EPCOS assumes no warranty or reliability for the combination of EPCOS ferrite accessories with cores and other accessories from any other manufacturer.

Processing remarks

The start of the winding process should be soft. Else the flanges may be destroyed.

- Too strong winding forces may blast the flanges or squeeze the tube that the cores can not be mounted any more.
- Too long soldering time at high temperature (>300 °C) may effect coplanarity or pin arrangement.
- Not following the processing notes for soldering of the J-leg terminals may cause solderability problems at the transformer because of pollution with Sn oxyde of the tin bath or burned insulation of the wire. For detailed information see chapter "Processing notes", section 2.2.
- The dimensions of the hole arrangement have fixed values and should be understood as a recommendation for drilling the printed circuit board. For dimensioning the pins, the group of holes can only be seen under certain conditions, as they fit into the given hole arrangement. To avoid problems when mounting the transformer, the manufacturing tolerances for positioning the customers' drilling process must be considered by increasing the hole diameter.

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Cautions and warnings

Display of ordering codes for EPCOS products

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications and the website of EPCOS, or in order-related documents such as shipping notes, order confirmations and product labels. The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products. Detailed information can be found on the Internet under www.epcos.com/orderingcodes.



Symbols and terms

Symbol	Meaning	Unit
A	Cross section of coil	mm ²
A_{e}	Effective magnetic cross section	mm ²
A_{L}	Inductance factor; A _L = L/N ²	nH
A_{L1}	Minimum inductance at defined high saturation ($\stackrel{\triangle}{=} \mu_a$)	nH
A_{min}	Minimum core cross section	mm ²
A_N	Winding cross section	mm ²
A_R	Resistance factor; $A_R = R_{Cu}/N^2$	$\mu\Omega = 10^{-6} \Omega$
В	RMS value of magnetic flux density	Vs/m ² , mT
ΔB	Flux density deviation	Vs/m ² , mT
Ê	Peak value of magnetic flux density	Vs/m ² , mT
ΔÂ	Peak value of flux density deviation	Vs/m ² , mT
B_DC	DC magnetic flux density	Vs/m ² , mT
B_R	Remanent flux density	Vs/m ² , mT
B_S	Saturation magnetization	Vs/m ² , mT
C_0	Winding capacitance	F = As/V
CDF	Core distortion factor	mm ^{-4.5}
DF	Relative disaccommodation coefficient DF = d/μ_i	
d	Disaccommodation coefficient	
E_a	Activation energy	J
f	Frequency	s ^{−1} , Hz
f _{cutoff}	Cut-off frequency	s ^{−1} , Hz
f _{max}	Upper frequency limit	s ^{−1} , Hz
f _{min}	Lower frequency limit	s ^{−1} , Hz
f _r	Resonance frequency	s ^{−1} , Hz
f_{Cu}	Copper filling factor	
g	Air gap	mm
Н	RMS value of magnetic field strength	A/m
Ĥ	Peak value of magnetic field strength	A/m
H_{DC}	DC field strength	A/m
H _c	Coercive field strength	A/m
h	Hysteresis coefficient of material	10 ⁻⁶ cm/A
h/μ_i^2	Relative hysteresis coefficient	10 ⁻⁶ cm/A
1	RMS value of current	Α
I_{DC}	Direct current	Α
î	Peak value of current	Α
J	Polarization	Vs/m ²
k	Boltzmann constant	J/K
k_3	Third harmonic distortion	
k _{3c}	Circuit third harmonic distortion	
L	Inductance	H = Vs/A



Symbols and terms

Symbol	Meaning	Unit
ΔL/L	Relative inductance change	Н
L_0	Inductance of coil without core	Н
L_H	Main inductance	Н
L_p	Parallel inductance	Н
L _{rev}	Reversible inductance	Н
L _s	Series inductance	Н
l _e	Effective magnetic path length	mm
I_N	Average length of turn	mm
N	Number of turns	
P_{Cu}	Copper (winding) losses	W
P _{trans}	Transferrable power	W
P_V	Relative core losses	mW/g
PF	Performance factor	
Q	Quality factor (Q = $\omega L/R_s$ = 1/tan δ_l)	
R	Resistance	Ω
R_{Cu}	Copper (winding) resistance (f = 0)	Ω
R _h	Hysteresis loss resistance of a core	Ω
ΔR_h	R _h change	Ω
R _i	Internal resistance	Ω
R_p	Parallel loss resistance of a core	Ω
R_s	Series loss resistance of a core	Ω
R _{th}	Thermal resistance	K/W
R_V	Effective loss resistance of a core	Ω
S	Total air gap	mm
Т	Temperature	°C
ΔT	Temperature difference	K
T_{C}	Curie temperature	°C
t	Time	s
t_v	Pulse duty factor	
tan δ	Loss factor	
tan δ_l	Loss factor of coil	
tan δ_r	(Residual) loss factor at H \rightarrow 0	
tan $\delta_{\rm e}$	Relative loss factor	
tan δ_h	Hysteresis loss factor	
tan δ/μ _i	Relative loss factor of material at H \rightarrow 0	
U	RMS value of voltage	V
Û	Peak value of voltage	V
V _e	Effective magnetic volume	mm ³
Z	Complex impedance	Ω
Z _n	Normalized impedance $ Z _n = Z /N^2 \times \varepsilon (I_e/A_e)$	Ω/mm

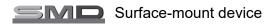
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Symbols and terms

Symbol	Meaning	Unit
α	Temperature coefficient (TK)	1/K
α_{F}	Relative temperature coefficient of material	1/K
α_{e}	Temperature coefficient of effective permeability	1/K
ε_{r}	Relative permittivity	
Φ	Magnetic flux	Vs
η	Efficiency of a transformer	
η_{B}	Hysteresis material constant	mT-1
η_{i}	Hysteresis core constant	$A^{-1}H^{-1/2}$
λ_{s}	Magnetostriction at saturation magnetization	
u	Relative complex permeability	
μ_0	Magnetic field constant	Vs/Am
l _a	Relative amplitude permeability	
$\mu_{\sf app}$	Relative apparent permeability	
μ_{e}	Relative effective permeability	
ι_{i}	Relative initial permeability	
ı _p '	Relative real (inductive) component of $\overline{\mu}$ (for parallel components)	
u _p "	Relative imaginary (loss) component of $\overline{\mu}$ (for parallel components)	
μ_{r}	Relative permeability	
\mathfrak{u}_{rev}	Relative reversible permeability	
ι _s '	Relative real (inductive) component of $\overline{\mu}$ (for series components)	
ι _s "	Relative imaginary (loss) component of $\overline{\mu}$ (for series components)	
ι_{tot}	Relative total permeability	
	derived from the static magnetization curve	
)	Resistivity	Ω m $^{-1}$
ΣΙ/Α	Magnetic form factor	mm ⁻¹
c _{Cu}	DC time constant $\tau_{Cu} = L/R_{Cu} = A_L/A_R$	s
ω	Angular frequency; ω = 2 Π f	s ⁻¹

All dimensions are given in mm.





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